

WHAT IS CLAIMED IS

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1. A method of fabricating a semiconductor device having a ferroelectric capacitor, comprising the steps of:

10 forming an active device element on a substrate;

forming an insulation film over said substrate to cover said active device element;

15 forming a lower electrode layer of said ferroelectric capacitor over said insulation film;

forming a ferroelectric film on said lower electrode layer as a capacitor insulation film of said ferroelectric capacitor;

20 crystallizing said ferroelectric film by applying a thermal annealing process in an atmosphere containing a non-oxidizing gas and an oxidizing gas; and

forming an upper electrode layer on said ferroelectric film.

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2. A method as claimed in claim 1, wherein said step of forming said lower electrode layer 30 includes a step of depositing a Ti layer and a Pt layer consecutively.

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3. A method as claimed in claim 1, wherein said step of crystallizing said ferroelectric film is

conducted by setting the composition of said atmosphere such that said atmosphere contains said oxidizing gas with a fraction of 1 - 50% in volume.

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4. A method as claimed in claim 1, wherein
said non-oxidizing gas is selected from a group
10 consisting of Ar, He, Ne, Xe and N₂.

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5. A method as claimed in claim 1, wherein
said oxidizing gas is selected from a group consisting
of O₂, N₂O, NO and NO₂.

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6. A method as claimed in claim 1, wherein
said step of crystallizing said ferroelectric film is
conducted by a rapid thermal annealing process.

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7. A method as claimed in claim 1, wherein
said step of forming said step of forming said
ferroelectric film comprises the step of forming said
ferroelectric film by a sputtering process.

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8. A method as claimed in claim 7, wherein

said ferroelectric film has a perovskite structure.

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9. A method as claimed in claim 8, wherein
said ferroelectric film is a film of zirconate
titanate of Pb.

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10. A method as claimed in claim 1, further
comprising the step, after said step of crystallizing
15 said ferroelectric film, of oxidizing said
ferroelectric film in an oxidizing atmosphere.

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11. A method as claimed in claim 1, wherein
said step of crystallizing said ferroelectric film is
conducted under a reduced total pressure.

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12. A method of fabricating a semiconductor
device having a ferroelectric capacitor, comprising
30 the steps of:

forming an active device element on a
substrate;

forming an insulation film over said
substrate to cover said active device element;

35 forming a lower electrode layer of said
ferroelectric capacitor over said insulation film;

forming a ferroelectric film on said lower

electrode layer as a capacitor insulation film of said ferroelectric capacitor;

crystallizing said ferroelectric film by applying a thermal annealing process in an atmosphere 5 of an oxidizing gas under a reduced total pressure smaller than an atmospheric pressure; and

forming an upper electrode layer on said ferroelectric film.

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13. A method as claimed in claim 1 wherein said oxidizing gas is O₂ and wherein said total 15 pressure is set in the range between 1 Torr and 40 Torr.

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14. A method of fabricating a semiconductor device having a ferroelectric capacitor, comprising the steps of:

25 forming an active device element on a substrate;

forming an insulation film over said substrate to cover said active device element;

30 forming a lower electrode layer of said ferroelectric capacitor over said insulation film, said lower electrode layer including a layer part containing Ti atoms;

forming a ferroelectric film on said lower electrode layer as a capacitor insulation film of said ferroelectric capacitor;

35 crystallizing said ferroelectric film by applying a thermal annealing process in an atmosphere of an oxidizing gas; and

forming an upper electrode layer on said ferroelectric film,

wherein said step of crystallizing said ferroelectric film is conducted by supplying O₂

5 controlled to cause an oxidation in said Ti atoms reached a surface of said lower electrode from said layer part containing Ti atoms.

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15. A semiconductor device, comprising:
a substrate;
an active device element formed on said
15 substrate;

an insulation film provided over said substrate to cover said active device element;

20 a lower electrode provided over said insulation film;

25 a ferroelectric film provided on said lower electrode, said ferroelectric film having a columnar microstructure extending from an interface between said lower electrode and said ferroelectric film in a direction substantially perpendicular to a principal 25 surface of said lower electrode, said ferroelectric film essentially consisting of crystal grains having a generally uniform grain diameter of less than about 200 nm; and

30 an upper electrode provided on said ferroelectric film.

35 16. A semiconductor device as claimed in claim 15, wherein said crystal grains constituting said ferroelectric film have an average diameter of

about 150 nm.

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17. A semiconductor device as claimed in
claim 15, wherein said lower electrode comprises a Ti
layer and a conductor layer provided further on said
Ti layer.

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18. A semiconductor device as claimed in
15 claim 17, wherein said conductor layer is formed of Pt.

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19. A semiconductor device as claimed in
claim 17, wherein said ferroelectric film has a
perovskite structure.

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20. A semiconductor device as claimed in
claim 19, wherein said ferroelectric film comprises a
zirconate titanate of Pb.

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